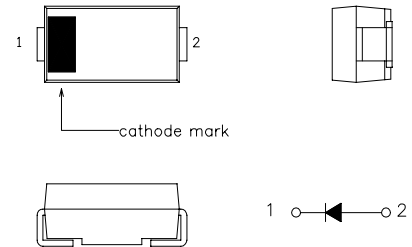


FRD Type : EC11FS2

FEATURES

- * Miniature Size, Surface Mount Device
- * Ultra-Fast Recovery
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC11FS2		Unit
Repetitive Peak Reverse Voltage	V_{RRM}	200		V
Non-repetitive Peak Reverse Voltage	V_{RSM}	220		V
Average Rectified Output Current	I_O	0.81	Ta=25°C *1	50Hz Half Sine Wave Resistive Load
		1.0	Ta=34°C *2	
RMS Forward Current	$I_{F(RMS)}$	1.57		A
Surge Forward Current	I_{FSM}	20	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	T_{jw}	-40 to +150		°C
Storage Temperature Range	T_{stg}	-40 to +150		°C

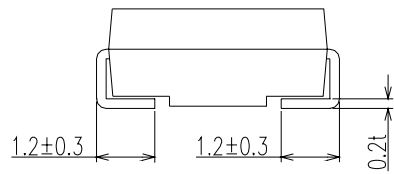
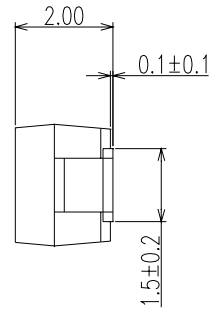
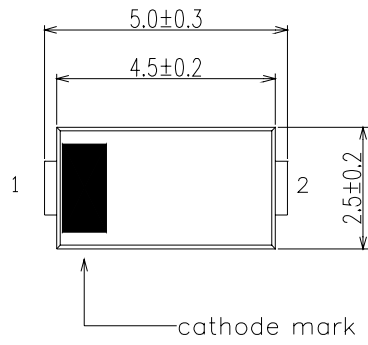
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I_{RM}	$T_j = 25^\circ\text{C}, V_{RM} = V_{RRM}$	-	-	10	μA	
Peak Forward Voltage	V_{FM}	$T_j = 25^\circ\text{C}, I_{FM} = 1.0\text{A}$	-	-	0.98	V	
Reverse Recovery Time	trr	$I_{FM} = 1\text{A}, -di/dt = 50\text{A}/\mu\text{s}, T_a = 25^\circ\text{C}$	-	-	30	ns	
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	157	°C/W
			*2	-	-	108	

*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

EC11FS2 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

